

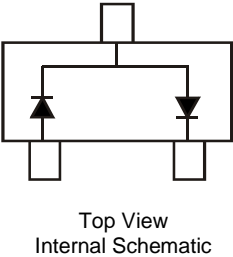
**DUAL SURFACE MOUNT LOW LEAKAGE DIODE**

### Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Suitable for Ultra-Low Leakage Current Applications, Including High-Precision Instrumentation And Portable Electronics
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

### Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin Finish Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

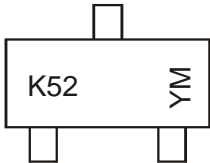


### Ordering Information (Notes 4 & 5)

Part Number	Compliance	Case	Packaging
BAV199WQ-7	Automotive	SOT323	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to [http://www.diodes.com/product\\_compliance\\_definitions.html](http://www.diodes.com/product_compliance_definitions.html).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

### Marking Information



K52= Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: D = 2016)  
 M = Month (ex: 9 = September)

Date Code Key

Year	2011	2012	2013	...	2016	2017	2018	2019	2020
Code	Y	Z	A	...	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	85	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	60	V
Forward Continuous Current (Note 6)	Single Diode	160	mA
	Double Diode	140	
Repetitive Peak Forward Current (Note 6)	I <sub>FRM</sub>	500	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	85	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	—	0.90	V	I <sub>F</sub> = 1.0mA
				1.0		I <sub>F</sub> = 10mA
				1.1		I <sub>F</sub> = 50mA
				1.25		I <sub>F</sub> = 150mA
Leakage Current (Note 7)	I <sub>R</sub>	—	—	5.0	nA	V <sub>R</sub> = 75V
				80		V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C
Total Capacitance	C <sub>T</sub>	—	2	—	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>RR</sub>	—	—	3.0	μs	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>RR</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 6. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
7. Short duration pulse test used to minimize self-heating effect.

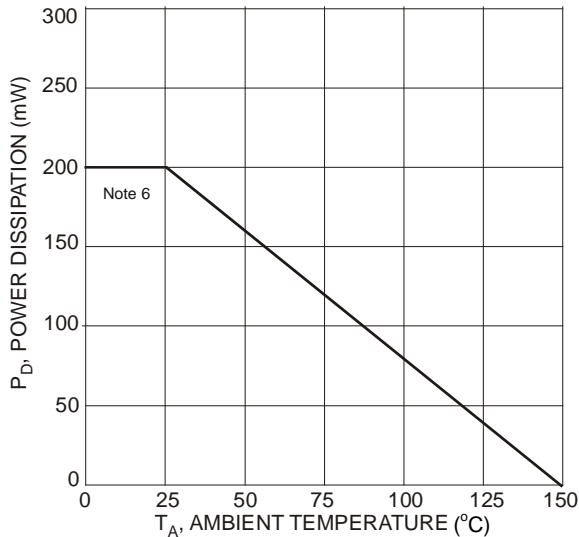


Fig. 1 Power Derating Curve, Total Package

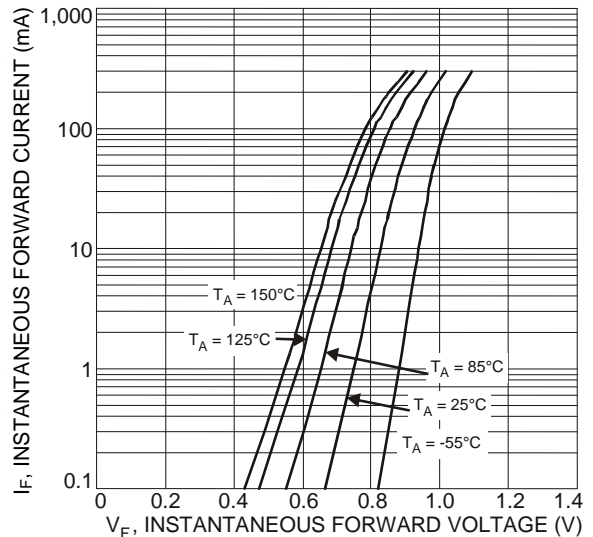
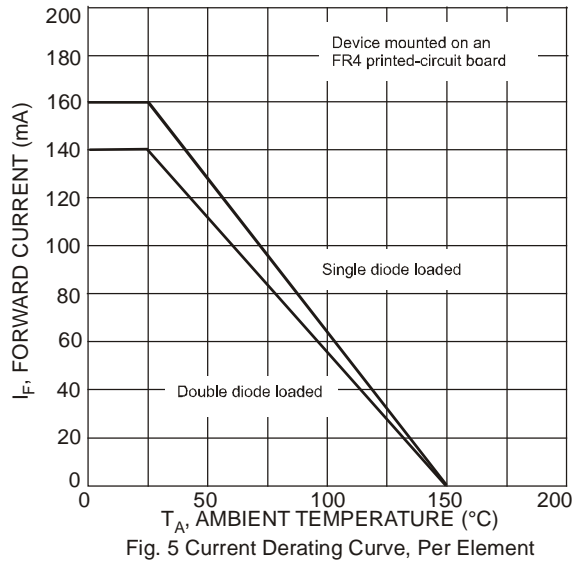
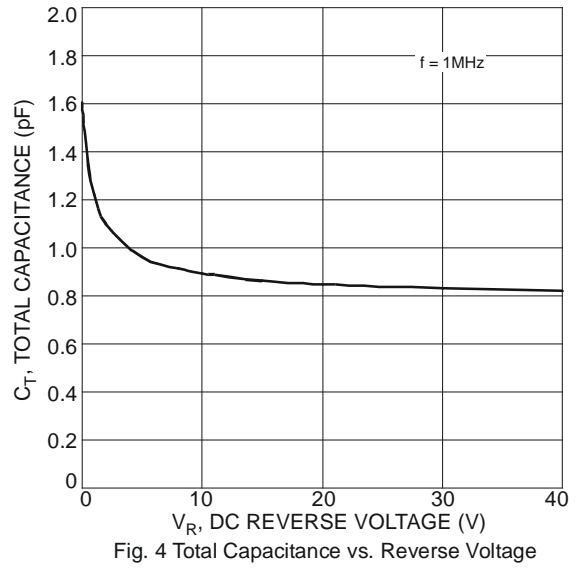
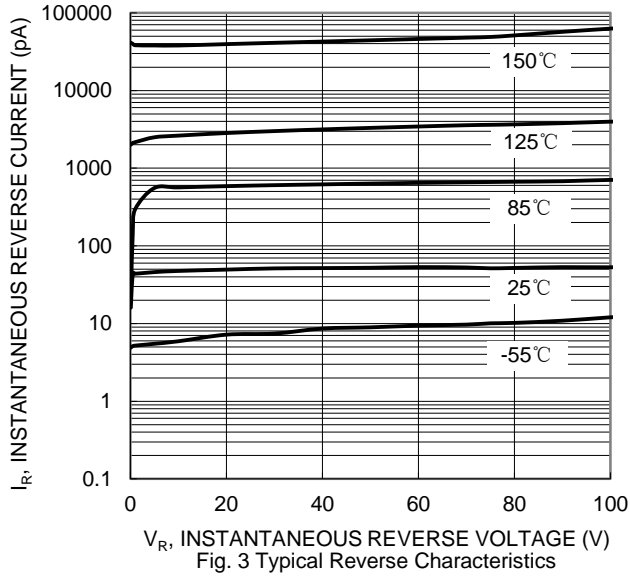


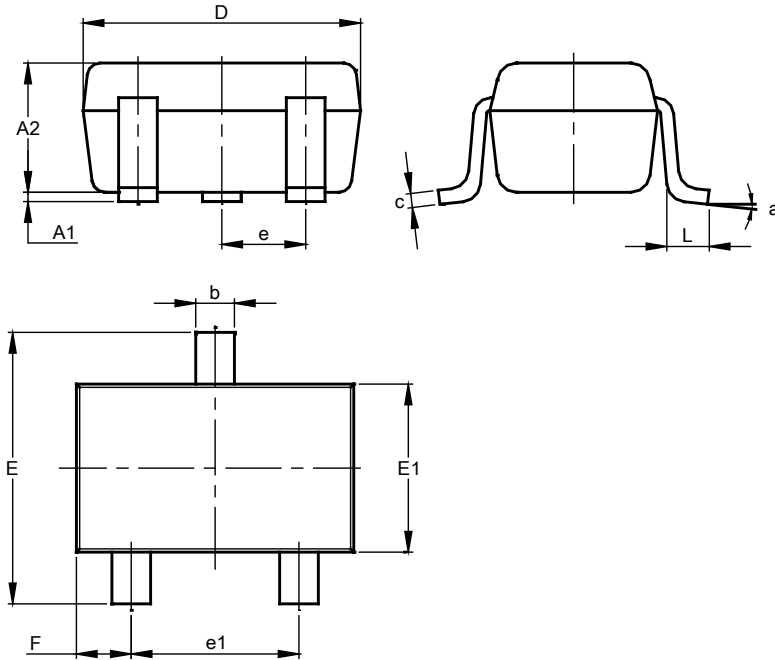
Fig. 2 Typical Forward Characteristics



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT323**

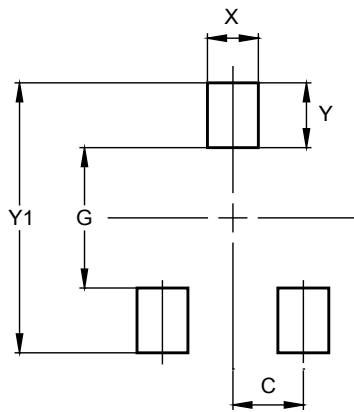


SOT323			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	0°	8°	--
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT323**



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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